

SPECIFICATION

PART NO: LA31H2450-A35**CUSTOMER PART NO:****CUSTOMER APPROVED BY:****APPROVED DATE:**

RoHS Compliant Parts

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Version rejigger track record

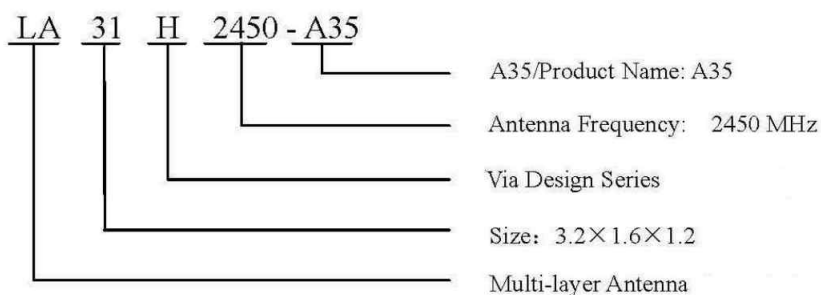
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Specification

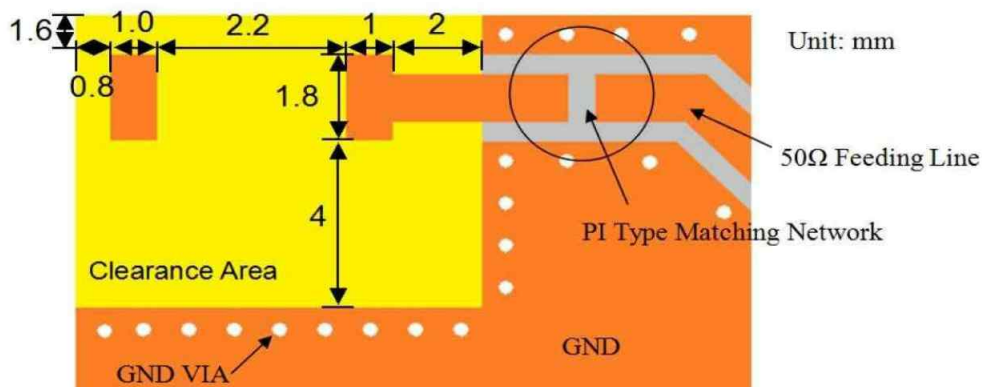
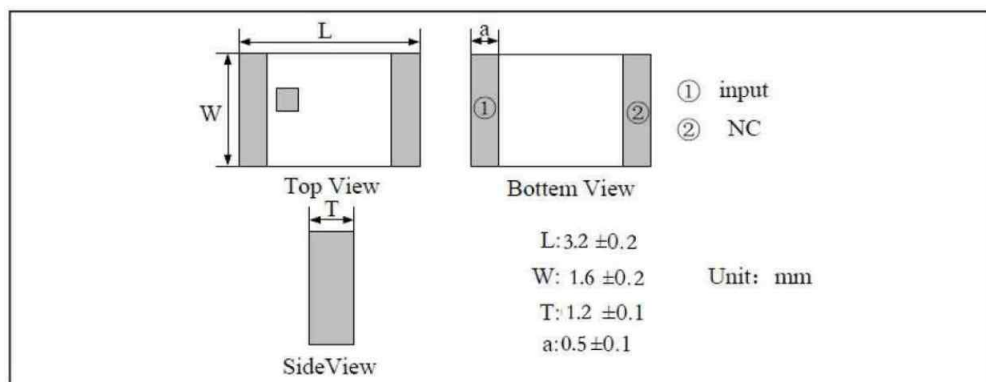
1. INTRODUCTION

"GLEAD" Microwave Multi-Layer Ceramic Antenna LA series are designed to be used in WLAN、WiFi、Bluetooth、PHS、 Multiple-band Mobile phone antenna, FM, etc and compact size SMD chip design.

2. Part Number

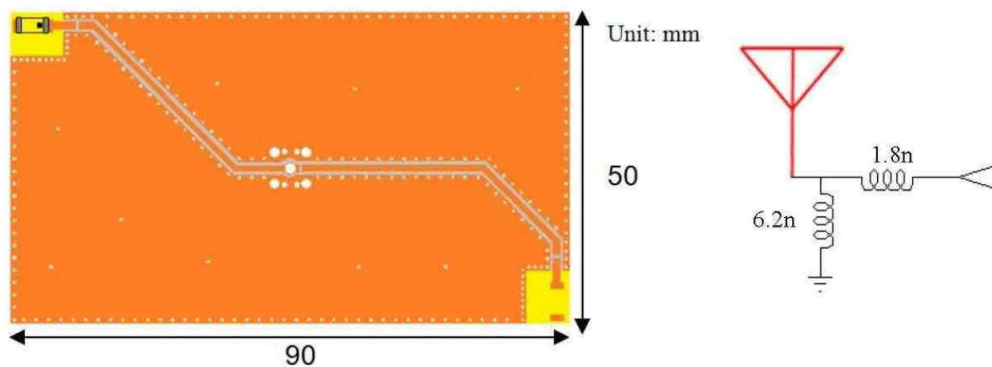


3. Dimensions (Unit: mm)



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4. Evaluation Board and Matching Circuits

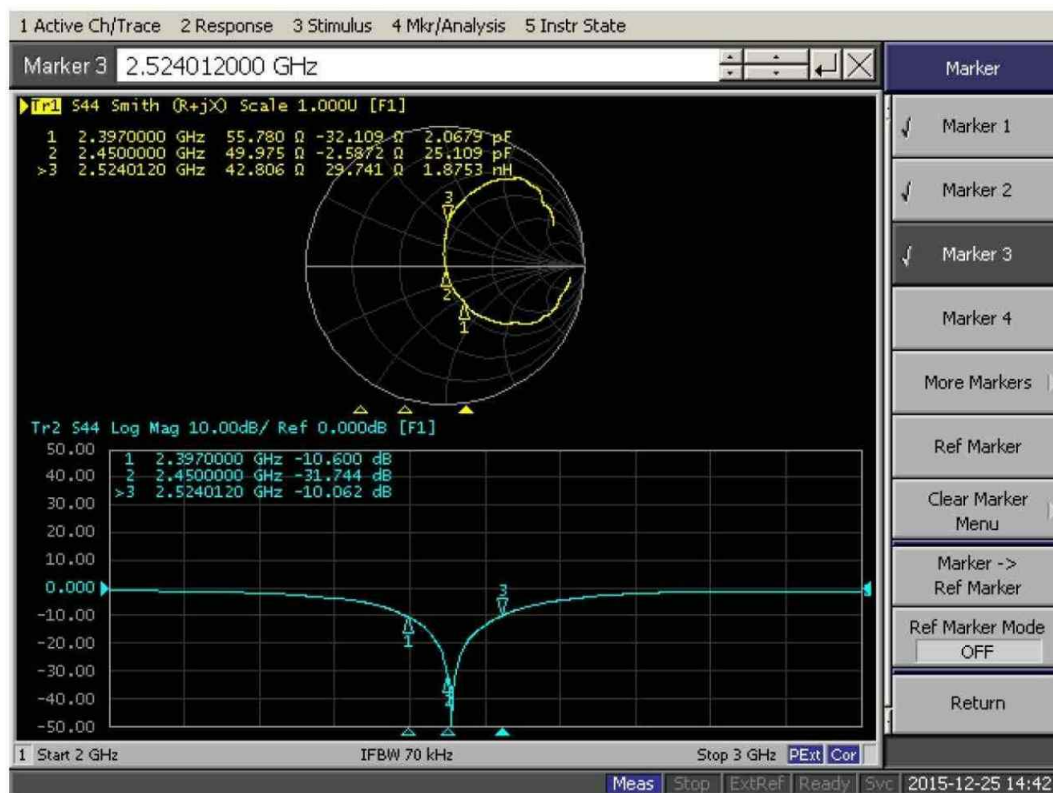


5. Electrical Characteristics

No.	Item	Specifications
5.1	Central Frequency (No matching)	2875 MHz
	After Matching	2450 MHz
5.2	Band Width	100MHz typ.
5.3	Peak Gain	5.19 dBi
5.4	V.S.W.R	≤ 2.0
5.5	Polarization	Linear
5.6	Azimuth Beam width	Omni-directional
5.7	Impedance	50 Ω

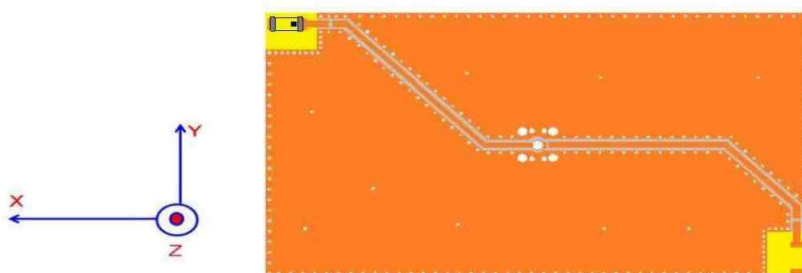
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6. Characteristic curve



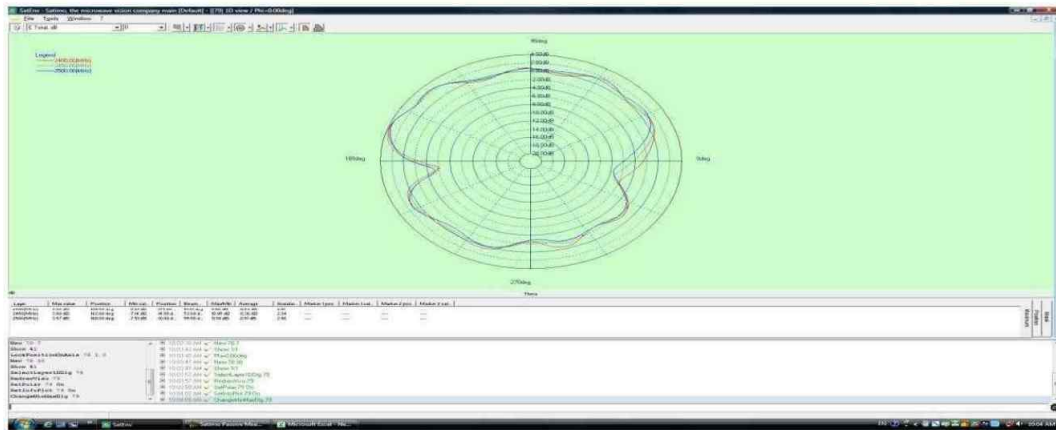
7. Radiation Pattern

coordinates:

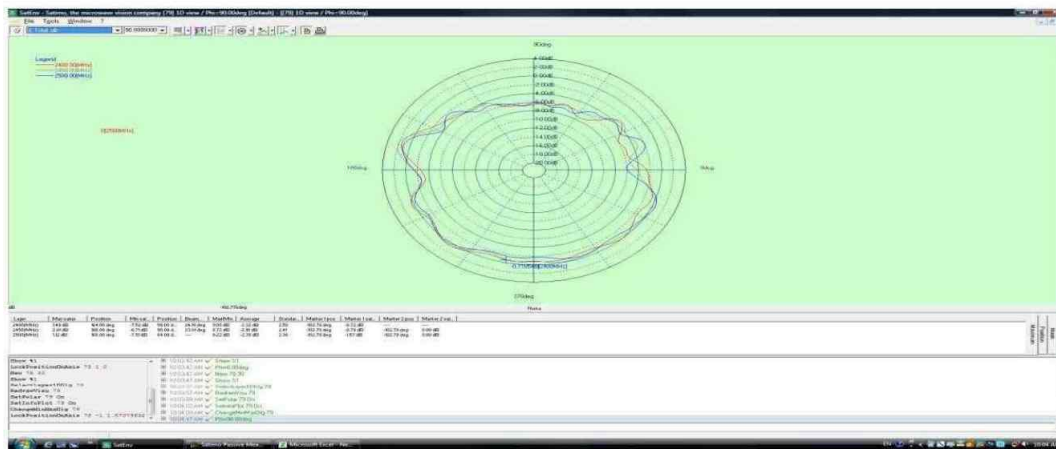


Specification

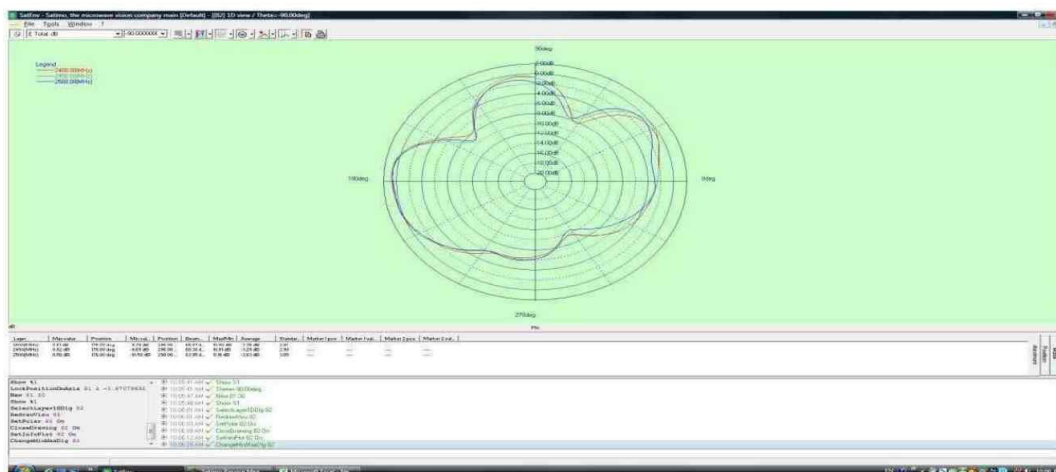
X-Z Plane



Y-Z Plane

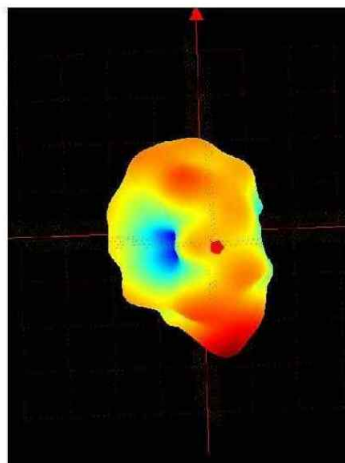


X-Y Plane



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3D Radiation Pattern



Frequency (MHz)	2400	2450	2500
Avg. Gain (dBi)	-0.23	-0.36	-0.51
Peck Gain (dBi)	4.98	5.19	4.55
Efficiency (%)	70	71.2	69

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8 Post Dependability Tolerance

Post Dependability Tolerance (Refer to the table)

No.	Item	Post Dependability Tolerance
8.1	Central Frequency	± 5 MHz
8.2	Band Width	± 5 MHz
8.3	Gain	± 0.1 dBi
8.4	V.S.W.R (in BW)	± 0.1

9 Dependability Test

Temperature range	$25 \pm 5^{\circ}\text{C}$
Relative Humidity range	55~75%RH
Operating Temperature range	$-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$

9.1 Vibration Resist

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X, Y and Z directions.

9.2 Drop Shock

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after dropping onto the hard wooden board from the height of 100cm for 3 times each facet of the 3 dimensions of the device.

9.3 Solder Heat Proof

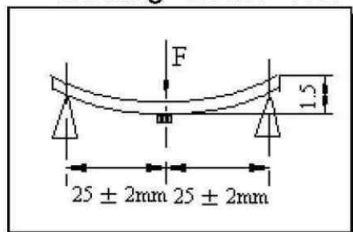
The device should be satisfied after preheating at $120^{\circ}\text{C} \sim 150^{\circ}\text{C}$ for 120 seconds and dipping in soldering Sn at $255^{\circ}\text{C} \pm 10^{\circ}\text{C}$ for 5 ± 0.5 seconds, or electric iron $300^{\circ}\text{C} - 10^{\circ}\text{C}$ for 3 ± 0.5 seconds, without damage.

9.4 Tensile Strength of Terminal

The device should not be broken after tensile force of 1.0kg is slowly applied to pull a lead pin of the fixed device in the lead axis direction for 10 ± 1 seconds.

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9.5 Bending Resist Test



Weld the product to the center part of the PCB with the thickness $1.6 \pm 0.2\text{mm}$ as the illustration shows, and keep exerting force arrow-ward on it at speed of 1mm/S , and hold for $5 \pm 1\text{s}$ at the position of 1.5mm bending distance, so far, any peeling off of the product metal coating should not be detected.

9.6 Moisture Proof

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the temperature $60 \pm 2^\circ\text{C}$ and the relative humidity $90\sim 95\%$ RH for 96 hours and 1~2 hours recovery time under normal condition.

9.7 High Temperature Endurance

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to temperature $85 \pm 5^\circ\text{C}$ for 96 ± 2 hours and 1~2 hours recovery time under normal temperature.

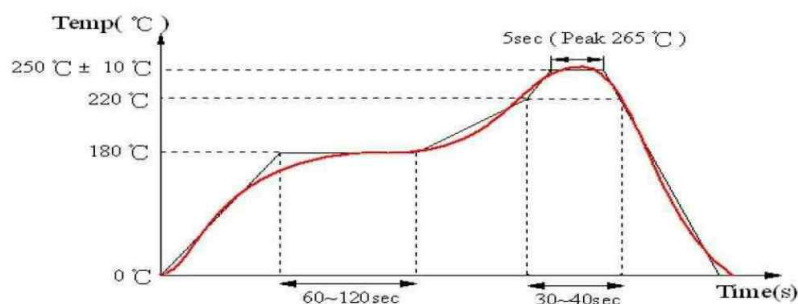
9.8 Low Temperature Endurance

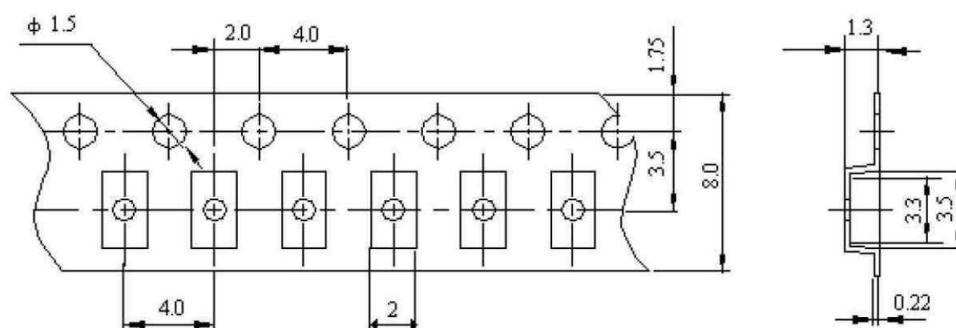
The device should also satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the temperature $-40^\circ\text{C} \pm 5^\circ\text{C}$ for 96 ± 2 hours and to 2 hours recovery time under normal temperature.

9.9 Temperature Cycle Test

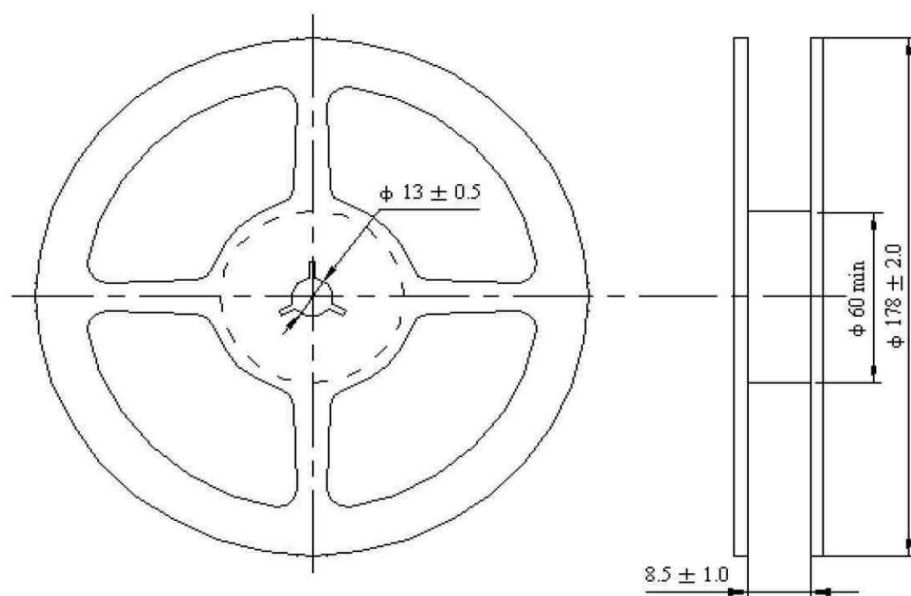
The device should also satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the low temperature -40°C and high temperature $+85^\circ\text{C}$ for 30 ± 2 min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

10 Reflow Soldering Standard Condition



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11 (3216) Packaging and Dimensions
11.1 Plastic Tape

Remarks for Package

Reserve a length of 150~200mm for the trailer of the carrier and 250~300 mm for the leader of the carrier and further 250mm of cover tape at the leading part of the carrier.

11.2 Reel (3000 pcs/Reel)

11.3 Storage Period

Oxidizable, 12 months in vacuum sealed bag . Material, please repack within 168 hours by re-seal the package treatment after use them!

Storage Temperature Range : <30 degree C, Humidity : <60%RH